



#### N-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

| V <sub>(BR)DSS</sub> | R <sub>DS(ON)</sub> max        | I <sub>D</sub> max<br>T <sub>A</sub> = +25°C |
|----------------------|--------------------------------|--|
|                      | 73mΩ @ V <sub>GS</sub> = 10V   | 3.3A   |
| 30V                  | 110mΩ @ V <sub>GS</sub> = 4.5V | 2.7A   |

# **Features and Benefits**

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/quality/product-definitions/

#### **Description and Applications**

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

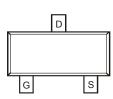
- General Purpose Interfacing Switch
- Power Management Functions
- Boost Application
- Analog Switch

#### **Mechanical Data**

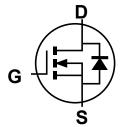
- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish—Matte Tin Annealed Over Copper Lead-Frame.
   Solderable per MIL-STD-202, Method 208 <sup>3</sup>
- Weight: 0.027 grams (approximate)



Top View



Pin Configuration



Internal Schematic

#### Ordering Information (Note 4)

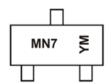
| Part Number | Case  | Packaging        |
|-------------|-------|------------------|
| DMN3110S-7  | SOT23 | 3000/Tape & Reel |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



# **Marking Information**



MN7 = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: I = 2021) M = Month (ex: 9 = September)

Date Code Key

| Year  | 2021 | 2022 | 2023 | 2024 | 2025 | 2026 | 2027 | 2028 | 2029 | 2030 | 2031 | 2032 |
|-------|------|------|------|------|------|------|------|------|------|------|------|------|
| Code  | I    | J    | K    | L    | М    | N    | 0    | Р    | R    | S    | T    | U    |
|       |      |      |      |      |      |      |      |      |      |      |      |      |
| Month | Jan  | Feb  | Mar  | Apr  | May  | Jun  | Jul  | Aug  | Sep  | Oct  | Nov  | Dec  |

# Maximum Ratings (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic   |                 | Symbol   | Value            | Units      |   |
|--|-----------------|--|------------------|------------|---|
| Drain-Source Voltage                                     |                 |  | $V_{DSS}$        | 30         | V |
| Gate-Source Voltage                                      |                 |  | V <sub>GSS</sub> | ±20        | V |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V  | Steady<br>State | T <sub>A</sub> = +25°C<br>T <sub>A</sub> = +70°C | I <sub>D</sub>   | 2.5<br>2.0 | А |
| Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V  | Steady<br>State | $T_A = +25^{\circ}C$<br>$T_A = +70^{\circ}C$     | I <sub>D</sub>   | 3.3<br>2.7 | Α |
| Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V  | t≦10sec         | $T_A = +25^{\circ}C$<br>$T_A = +70^{\circ}C$     | I <sub>D</sub>   | 3.8<br>3.1 | Α |
| Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V | I <sub>D</sub>  | 2.7<br>2.1                                       | А                |            |   |
| Pulsed Drain Current (Note 7)                            | •               |  | I <sub>DM</sub>  | 25         | Α |

# Thermal Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic   | Symbol                            | Value       | Units |
|--|-----------------------------------|-------------|-------|
| Total Power Dissipation (Note 5)                         | P <sub>D</sub>                    | 0.74        | W     |
| Thermal Resistance, Junction to Ambient (Note 5)         | $R_{	heta JA}$                    | 173.4       | °C/W  |
| Total Power Dissipation (Note 6)                         | P <sub>D</sub>                    | 1.3         | W     |
| Thermal Resistance, Junction to Ambient (Note 6)         | $R_{	heta JA}$                    | 99.1        | °C/W  |
| Total Power Dissipation (Note 6) t≦10sec                 | P <sub>D</sub>                    | 1.8         | W     |
| Thermal Resistance, Junction to Ambient (Note 6) t≦10sec | $R_{\theta JA}$                   | 72          | °C/W  |
| Operating and Storage Temperature Range                  | T <sub>J</sub> , T <sub>STG</sub> | -55 to +150 | °C    |

Notes:

5. Device mounted on FR-4 PCB, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, on 1inch square copper plate
7. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%



# Electrical Characteristics (@ T<sub>A</sub> = +25°C, unless otherwise specified.)

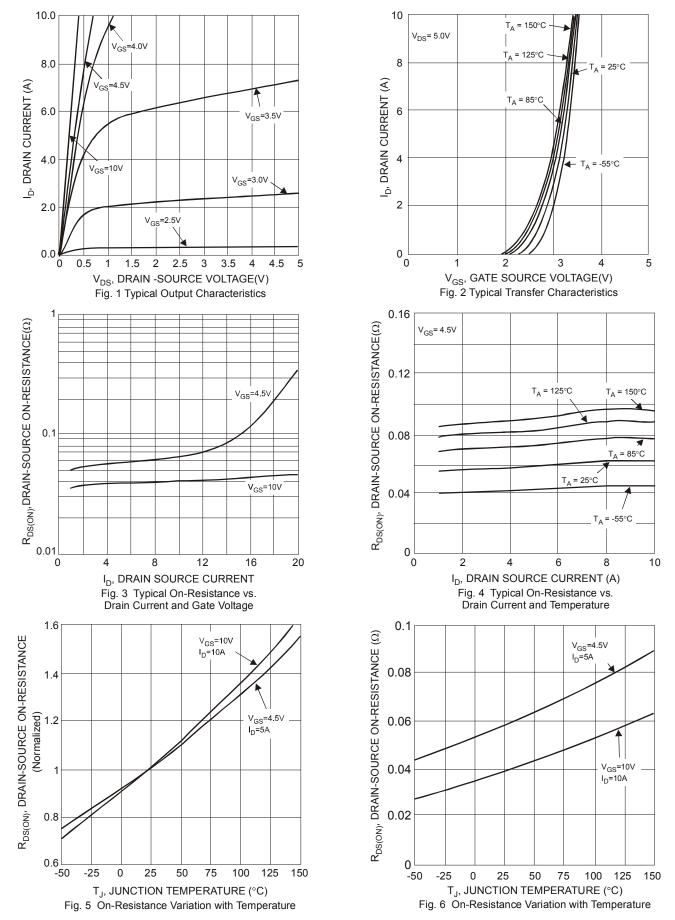
| Characteristic                             |                              | Symbol               | Min | Тур   | Max  | Unit  | Test Condition   |
|--|------------------------------|----------------------|-----|-------|------|-------|--|
| OFF CHARACTERISTICS (Note 8)               | OFF CHARACTERISTICS (Note 8) |                      |     |       |      |       |  |
| Drain-Source Breakdown Voltage             |                              | $BV_{DSS}$           | 30  | -     | -    | V     | $V_{GS} = 0V, I_D = 250\mu A$                              |
| Zero Gate Voltage Drain Current            | @T <sub>C</sub> = +25°C      | I <sub>DSS</sub>     | -   | -     | 1.0  | μA    | V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V                |
| Gate-Source Leakage                        |                              | I <sub>GSS</sub>     | -   | -     | ±100 | nA    | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V               |
| ON CHARACTERISTICS (Note 8)                |                              |                      |     |       |      |       |  |
| Gate Threshold Voltage                     |                              | $V_{GS(th)}$         | 1.0 | -     | 3.0  | ٧     | $V_{DS} = V_{GS}$ , $I_D = 250\mu A$                       |
| Static Drain-Source On-Resistance          |                              | ם                    | -   | 54    | 73   | mΩ    | V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.1A               |
| Static Diain-Source On-Resistance          |                              | R <sub>DS (ON)</sub> | 1   | 88    | 110  | 11122 | $V_{GS} = 4.5V, I_D = 2A$                                  |
| Forward Transfer Admittance                |                              | Y <sub>fs</sub>      | -   | 4.8   | -    | mS    | V <sub>DS</sub> = 10V, I <sub>D</sub> = 3.1A               |
| Diode Forward Voltage (Note 6)             |                              | $V_{SD}$             | 1   | 0.75  | 1.0  | V     | V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A                  |
| DYNAMIC CHARACTERISTICS (Note 9)           |                              |                      |     |       |      |       |  |
| Input Capacitance                          |                              | C <sub>iss</sub>     | ı   | 305.8 | -    | pF    |  |
| Output Capacitance                         |                              | $C_{oss}$            | -   | 39.9  | -    | pF    | V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V,<br>f = 1.0MHz |
| Reverse Transfer Capacitance               |                              | $C_{rss}$            | -   | 39.5  | -    | pF    | 1 - 1.0WH12  |
| Gate Resistance                            |                              | $R_g$                | -   | 1.4   | -    | Ω     | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$                     |
| Total Gate Charge (V <sub>GS</sub> = 4.5V) |                              | $Q_g$                | -   | 4.1   | -    | nC    |  |
| Total Gate Charge (V <sub>GS</sub> = 10V)  |                              | $Q_g$                | -   | 8.6   | -    | nC    | $V_{GS} = 10V, V_{DS} = 10V,$                              |
| Gate-Source Charge                         |                              | Q <sub>gs</sub>      | -   | 1.2   | -    | nC    | $I_D = 3A$   |
| Gate-Drain Charge                          |                              | Q <sub>gd</sub>      | -   | 1.5   | -    | nC    | ]  |
| Turn-On Delay Time                         |                              | t <sub>D(on)</sub>   | -   | 2.6   | -    | ns    |  |
| Turn-On Rise Time                          |                              | tr                   | 1   | 4.6   | -    | ns    | V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V,              |
| Turn-Off Delay Time                        |                              | $t_{D(off)}$         | -   | 13.1  | -    | ns    | $R_L = 47\Omega$ , $R_G = 3\Omega$ ,                       |
| Turn-Off Fall Time                         |                              | t <sub>f</sub>       | -   | 2.5   | -    | ns    |  |

Notes:

<sup>8.</sup> Short duration pulse test used to minimize self-heating effect.

<sup>9.</sup> Guaranteed by design. Not subject to product testing.







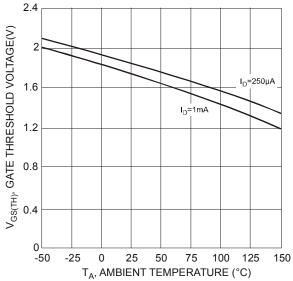
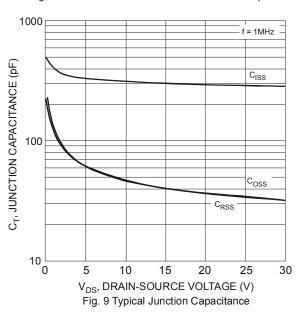
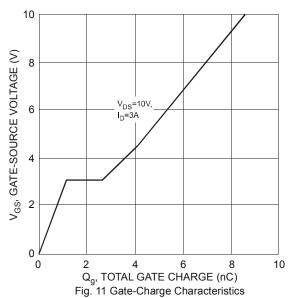
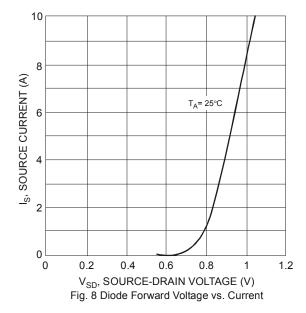
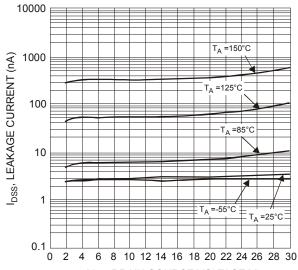


Fig. 7 Gate Threshold Variation vs. Ambient Temperature



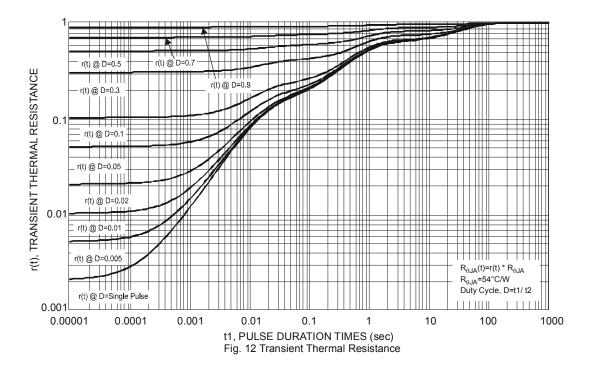






V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE(V)
Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

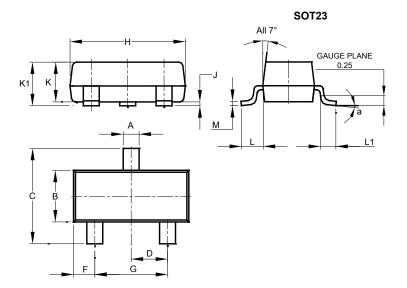






# **Package Outline Dimensions**

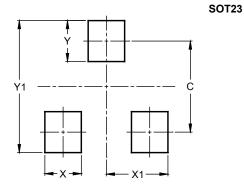
Please see http://www.diodes.com/package-outlines.html for the latest version.



| SOT23                |       |       |       |  |  |  |  |
|----------------------|-------|-------|-------|--|--|--|--|
| Dim                  | Min   | Max   | Тур   |  |  |  |  |
| Α                    | 0.37  | 0.51  | 0.40  |  |  |  |  |
| В                    | 1.20  | 1.40  | 1.30  |  |  |  |  |
| С                    | 2.30  | 2.50  | 2.40  |  |  |  |  |
| D                    | 0.89  | 1.03  | 0.915 |  |  |  |  |
| F                    | 0.45  | 0.60  | 0.535 |  |  |  |  |
| G                    | 1.78  | 2.05  | 1.83  |  |  |  |  |
| Н                    | 2.80  | 3.00  | 2.90  |  |  |  |  |
| J                    | 0.013 | 0.10  | 0.05  |  |  |  |  |
| K                    | 0.890 | 1.00  | 0.975 |  |  |  |  |
| K1                   | 0.903 | 1.10  | 1.025 |  |  |  |  |
| L                    | 0.45  | 0.61  | 0.55  |  |  |  |  |
| L1                   | 0.25  | 0.55  | 0.40  |  |  |  |  |
| М                    | 0.085 | 0.150 | 0.110 |  |  |  |  |
| а                    | 0°    | 8°    |       |  |  |  |  |
| All Dimensions in mm |       |       |       |  |  |  |  |

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



| Dimensions | Value (in mm) |
|------------|---------------|
| С          | 2.0           |
| Х          | 0.8           |
| X1         | 1.35          |
| Υ          | 0.9           |
| Y1         | 2.9           |



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